AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-26. (Cancelled)

27. **(Currently Amended)** An optical semiconductor package, comprising:

a substrate having opposite upper and lower surfaces;

a chip disposed on the upper surface of said substrate and having an optical element on an upper surface of said chip;

a plurality of bonding pads disposed on the upper surface of said substrate;

a plurality of bonding wires electrically connecting the chip to the bonding pads;

a transparent adhesive layer;

a window made of a transparent material mounted on the optical sensor of the chip by said transparent adhesive layer which is disposed between said window and said optical sensor for allowing light to transmit through the window and interact with the optical sensor; and

an encapsulant formed on the substrate for fixing the window and encapsulating the chip and the bonding wires;

wherein

said window has opposite upper and lower surfaces and a side surface connecting the upper and lower surfaces of said window;

said transparent adhesive layer directly, physically contacts both the lower surface of said window and an upper surface of said optical sensor of said chip and attaches the lower surface of

said window and the upper surface of said optical sensor together; and

said encapsulant surrounds said window and directly, physically contacts the side surface of said window, while leaving the upper surface of said window exposed from an upper surface of said encapsulant wherein said encapsulant and said adhesive layer are made of different materials.

28. (Cancelled)

29. **(Currently Amended)** An optical semiconductor package, comprising:

a substrate having opposite upper and lower surfaces;

a chip disposed on the upper surface of said substrate and having an optical sensor;

a plurality of bonding wires electrically connecting the chip to the substrate;

a supporting wall extending upwardly from the upper surface of said substrate;

a window made of a transparent material and supported by said supporting wall at a location above said optical sensor for allowing light to transmit through the window and interact with the optical sensor; and

an encapsulant formed on the upper surface of said substrate to surround said supporting wall[[.]];

wherein said supporting wall comprises:

a first section extending upwardly from the upper surface of said substrate and inwardly toward the window, said first section having opposite upper and lower ends, the lower end being on the upper surface of said substrate;

a second section extending inwardly from the upper end of the first section, said second section supporting thereon said window; and

a third section extending upwardly from the lower end of said first section and outwardly

away from the window, said third section being embedded in said encapsulant;

wherein said first and third sections define together a cavity located between two upper surfaces of the first section and the third section which surfaces are parallel to the substrate, said cavity receiving therein a portion of said encapsulant.

30. (Previously Presented) The optical semiconductor package as claimed in claim 29, wherein said encapsulant includes

an outer portion covering an outer side surface of said supporting wall; and

an inner portion encapsulating said chip and said wires and covering an inner side surface of said supporting wall, wherein said inner portion of said encapsulant is transparent.

31. (Previously Presented) The optical semiconductor package as claimed in claim 29, wherein said encapsulant, said supporting wall, said window and said substrate together define a hermetically sealed cavity in which said chip, said optical sensor and said wires are disposed.

32. (Previously Presented) The optical semiconductor package as claimed in claim 27, wherein the encapsulant is made of an opaque material.

33. (Previously Presented) The optical semiconductor package as claimed in claim 32, wherein the window is a lens.

34. (Previously Presented) The optical semiconductor package as claimed in claim 27, comprising a straight light path that extends from the upper surface of said window to the

upper surface of said optical sensor and through said window and said adhesive layer only, wherein said light path does not extend through said encapsulant.

35. **(Cancelled)**